







APPLICABLE STANDARD					
RATING	OPERATING TEMPERATURE RANGE	-55 °C TO 85 °C <sup>(1)</sup>	STORAGE TEMPERATURE RANGE	-10 °C TO 60 °C <sup>(2)</sup>	
	VOLTAGE	100 V AC	STORAGE HUMIDITY RANGE	40 % TO 70 % <sup>(2)</sup>	
	CURRENT	0.5 A (SIGNAL CONTACT) <sup>(3)</sup> 3 A (MF CONTACT) 	OPERATING HUMIDITY RANGE	RELATIVE HUMIDITY 85% max (NOT DEWED)	
<b>SPECIFICATIONS</b>					
ITEM	TEST METHOD		REQUIREMENTS	QT	AT
<b>CONSTRUCTION</b>					
GENERAL EXAMINATION	VISUALLY AND BY MEASURING INSTRUMENT.		ACCORDING TO DRAWING.	x	x
MARKING	CONFIRMED VISUALLY.			x	x
<b>ELECTRIC CHARACTERISTICS</b>					
CONTACT RESISTANCE	100 mA(DC OR 1000Hz)		SIGNAL CONTACT : 90 mΩ MAX. MF CONTACT : 30 mΩ MAX. 	x	-
INSULATION RESISTANCE	250 V DC.		1000 MΩ MIN.	x	-
VOLTAGE PROOF	300 V AC FOR 1 min.		NO FLASHOVER OR BREAKDOWN.	x	-
<b>MECHANICAL CHARACTERISTICS</b>					
INSERTION AND WITHDRAWAL FORCES	MEASURED BY APPLICABLE CONNECTOR.		INSERTION FORCE: 70 N MAX. WITHDRAWAL FORCE: 7 N MIN.	x	-
MECHANICAL OPERATION	500 TIMES INSERTIONS AND EXTRACTIONS.		① CONTACT RESISTANCE: SIGNAL CONTACT : 100 mΩ MAX. MF CONTACT : 40 mΩ MAX.  ② NO DAMAGE, CRACK AND LOOSENESS OF PARTS.	x	-
VIBRATION	FREQUENCY 10 TO 55 TO 10Hz, APPROX 5min SINGLE AMPLITUDE : 0.75 mm, 10 CYCLES FOR 3 DIRECTIONS.		① NO ELECTRICAL DISCONTINUITY OF 1 μs. ② NO DAMAGE, CRACK AND LOOSENESS OF PARTS.	x	-
SHOCK	490 m/s <sup>2</sup> , DURATION OF PULSE 11 ms AT 3 TIMES FOR 3 DIRECTIONS.			x	-
<b>ENVIRONMENTAL CHARACTERISTICS</b>					
DAMP HEAT (STEADY STATE)	EXPOSED AT 40±2 °C, 90 ~ 95 %, 96 h.		① CONTACT RESISTANCE: SIGNAL CONTACT : 100 mΩ MAX. MF CONTACT : 40 mΩ MAX. 	x	-
RAPID CHANGE OF TEMPERATURE	TEMPERATURE -55 → +85 °C TIME 30 → 30 min. UNDER 5 CYCLES. (RELOCATION TIME TO CHAMBER: WITHIN 2~3 MIN)		② INSULATION RESISTANCE : 1000 MΩ MIN. ③ NO DAMAGE, CRACK AND LOOSENESS OF PARTS.	x	-
SULFUR DIOXIDE	EXPOSED AT 25±2°C, 75±5%RH, 25 PPM FOR 96 h. (TEST STANDARD: JIS C 60068)		NO HEAVY CORROSION.	x	-
RESISTANCE TO SOLDERING HEAT	1)REFLOW SOLDERING : PEAK TMP : 260°C MAX REFLOW TMP: 220°C MIN FOR 60sec 2) SOLDERING IRONS : 360°C MAX. FOR 5 sec.		NO DEFORMATION OF CASE OF EXCESSIVE LOOSENESS OF THE TERMINAL.	x	-
SOLDERABILITY	SOLDERED AT SOLDER TEMPERATURE 240±3°C FOR IMMERSION DURATION, 3 sec.		A NEW UNIFORM COATING OF SOLDER SHALL COVER A MINIMUM OF 95 % OF THE SURFACE BEING IMMersed.	x	-
	COUNT	DESCRIPTION OF REVISIONS	DESIGNED	CHECKED	DATE
	4	DIS-F-004173	TH. SAN0	KI. HIROKAWA	09. 09. 15
REMARKS <sup>(1)</sup> INCLUDE TEMPERATURE RISE CAUSED BY CURRENT-CARRYING. <sup>(2)</sup> "STORAGE" MEANS A LONG-TERM STORAGE STATE FOR THE UNUSED PRODUCT BEFORE ASSEMBLY TO PCB. <sup>(3)</sup> THE RATED CURRENT APPLIES TO PER CONTACT. APPLY 0.4A WHEN ALL THE CONTACTS ARE USED FOR CURRENT CARRYING. Unless otherwise specified, refer to JIS-C-5402.			APPROVED	HS. OKAWA	09. 04. 28
			CHECKED	HS. OZAWA	09. 04. 28
			DESIGNED	KI. HIROKAWA	09. 04. 28
			DRAWN	KI. HIROKAWA	09. 04. 28
Note QT:Qualification Test AT:Assurance Test X:Applicable Test			DRAWING NO.	ELC4-159078-00	
	SPECIFICATION SHEET		PART NO.	FX18-120P-0. 8SH	
	HIROSE ELECTRIC CO., LTD.		CODE NO.	CL579-0006-6-00	